Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S54	20	((((package and die and (encapsul$4 or capsul$4 or cover$3 or cap or lid) and edg$3 and ball near grid with array) and wir$3 near2 bond$3) and adhesi$4 near2 layer) and spacer) and past$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/04 08:27
S56	3	"10/118570"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/03 20:31
S57	1	10/785448	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/03 20:32
S58	15332	(257/787,678,684,685,686,687, 692,704,707,710,730,780781,782, 783,784,788,790).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/03 20:58
S59	9653	(438/112,124,127,106,121,109, 125,614,118,617,126).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/03 20:59
S60	15703	package and die and (capsul$4 or cover$3 or cap or lid) and edg$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/03 20:59
S61	1599	S58 and (package and die and (capsul$4 or cover$3 or cap or lid) and edg$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/03 21:01
S62	420	S61 and extend$3 near6 edge	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/03 21:01
S63	2565	package and die and (encapsul$4 or capsul$4 or cover$3 or cap or lid) and edg$3 and ball near grid with array	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/03 21:02

S64	133	S62 and extend$3 near6 edge and ball near2 grid with array	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/03 21:44
S65	6	(("6492717") or ("6531784") or ("6564454")).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/03 21:47
S66	1100	((438/112,124,127,106,121,109, 125,614,118,617,126).CCLS.) and (package and die and (capsul$4 or cover$3 or cap or lid) and edg$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/04 08:27
S67	11	S66 and (((((package and die and (encapsul$4 or capsul$4 or cover$3 or cap or lid) and edg$3 and ball near grid with array) and wir$3 near2 bond$3) and adhesi$4 near2 layer) and spacer) and past$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/04 08:31
S68	1183	(connect$3 near3 wir$3 adj bond$3) near5 substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/04 08:41
S69	710	outer adj portion near3 substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/04 08:33
S70	14	S69 with width	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/04 08:33
S71	0	S67 and S70	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/04 08:33
S72	2	S68 and S70	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/04 08:34
S73	11	S66 and S69	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/04 08:34

S74	26	connect$3 near5 ((first near end) near3 (wir$3 adj bond$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/04 08:43
S75	9	(connect$3 near5 ((first near end) near3 (wir$3 adj bond$3))) near5 (die chip device)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/04 08:46
S76	4	(connect$3 near5 ((second near end) near3 (wir$3 adj bond$3))) near5 (substrate base board)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/04 08:44
S77	4	(connect$3 near5 ((second near end) near3 (wir$3 adj bond$3))) near5 (substrate base board plate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/04 08:45
S78	3	S74 and S77	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/04 08:45
S79	13482	(connect$3 near3 (die chip device)) near3 substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/04 09:03
S80	1238	adhesive near3 surface near (die chip device)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/04 09:04
S81	171381	(support layer) near2 adhesive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/04 09:04
S82	17794	paste near3 (substrate board plate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/04 09:11
S83	10	S79 with S80	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/04 09:10

S84	3	S83 with S81	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/04 09:12
S85	0	S84 with S82	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/04 09:12
S86	43547	paste with (substrate board plate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/04 09:11
S87	0	S84 with S86	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/04 09:12
S88	0	S84 same S82	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/04 09:12
S89	17983	19and S82	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/04 09:12
S90	0	S84 and S82	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/04 09:12
S91	0	S84 and S86	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/04 09:12